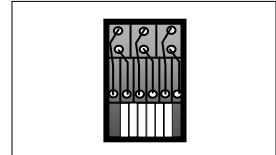


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## Vodafone W-CDMA Access Gateway Femtocell Model 253104761

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## TABLE OF CONTENTS

|   |    |
|---|----|
| EXECUTIVE SUMMARY .....                                   | 5  |
| Active/Passive Component Summary .....                    | 5  |
| Important Note: .....                                     | 5  |
| CHAPTER 1: W-CDMA/HSPA FEMTOCELL .....                    | 6  |
| 1.1 Overview of Femtocell Overlay .....                   | 6  |
| CHAPTER 2: VODAFONE ACCESS GATEWAY .....                  | 8  |
| 2.1 Product Analysis .....                                | 8  |
| 2.2 Mechanical Analysis .....                             | 10 |
| 2.3 System Architecture Analysis .....                    | 13 |
| CHAPTER 3: FEMTOCELL .....                                | 15 |
| APPENDIX A - PASSIVE CASE SIZE ANALYSIS.....              | 33 |
| APPENDIX B - ACTIVE COMPONENT MARKET SHARE ANALYSIS ..... | 35 |

# TABLES

|  |    |
|--|----|
| Table 1: Area A Bill of Materials .....  | 19 |
| Table 2: Area B Bill of Materials .....  | 21 |
| Table 3: Area C Bill of Materials .....  | 23 |
| Table 4: Area D Bill of Materials .....  | 25 |
| Table 5: Area E Bill of Materials .....  | 27 |
| Table 6: Area F Bill of Materials .....  | 29 |
| Table 7: SAGEM Communications GSM/GPRS Module Bill of Materials .....                | 32 |
| Table 8: Active/Passive Component Distribution by System Subsection.....             | 33 |
| Table 9: Passive Component Case Size Distribution by System Subsection (con't) ..... | 34 |
| Table 10: Active Semiconductor Vendor Distribution by System Subsection.....         | 36 |

# EXHIBITS

|   |    |
|---|----|
| Exhibit 1: Femtocell Overlay Deployment with Macrocell Underlay Network Diagram ..... | 7  |
| Exhibit 2: Vodafone Access Gateway Product .....                                      | 8  |
| Exhibit 3: BSR Femto Front Cover, External and Internal Views .....                   | 10 |
| Exhibit 4: BSR Femto Rear Cover, External and Internal Views .....                    | 11 |
| Exhibit 5: BSR Femto Internal Case, Front and Rear Views .....                        | 11 |
| Exhibit 6: BSR Femto, Front and Rear Views .....                                      | 12 |
| Exhibit 7: BSR Femto PCB, Top View .....  | 13 |
| Exhibit 8: BSR Femto PCB, Bottom View .....   | 14 |
| Exhibit 9: BSR Femtocell PCB, Top View .....  | 16 |
| Exhibit 10: BSR Femtocell PCB, Bottom View .....                                      | 17 |
| Exhibit 11: Area A Component Diagram .....  | 18 |
| Exhibit 12: Area B Component Diagram .....  | 20 |
| Exhibit 13: Area C Component Diagram .....  | 22 |
| Exhibit 14: W-CDMA TRx Block Diagram .....  | 22 |
| Exhibit 15: Area D Component Diagram .....  | 24 |
| Exhibit 16: Area E Component Diagram .....  | 26 |
| Exhibit 17: Area F Component Diagram .....  | 28 |
| Exhibit 18: SAGEM Communications GSM/GPRS Module w/ Shield .....                      | 30 |
| Exhibit 19: SAGEM Communications GSM/GPRS Module Component Diagram .....              | 31 |
| Exhibit 20: SAGEM Communications GSM/GPRS Module PCB, Bottom View .....               | 31 |
| Exhibit 21: Passive Component Case Size Distribution .....                            | 33 |
| Exhibit 23: Active Semiconductor Component Share .....                                | 35 |
| Exhibit 24: Active Semiconductor Market Share by Vendor .....                         | 37 |
| Exhibit 25: IC (>8 pin) vs. Discrete Active Semiconductor Share .....                 | 37 |
| Exhibit 26: High Pin Count (64+) Active Semiconductor Market Share by Vendor .....    | 38 |